

MN101D09E

Type	MN101D09E	MN101DF09G
Internal ROM type	Mask ROM	FLASH
ROM (byte)	80K	128K
RAM (byte)	2K	4K
Package (Lead-free)	QFP100-P-1818B	
Minimum Instruction Execution Time	[With main clock operated] 0.1397 μ s (at 4.0 V to 5.5 V, 14.32 MHz) 71.5 μ s (at 2.7 V to 5.5 V, 14.32 MHz internal frequency di Vision) [When sub-clock operated] 61 μ s (at 2.5 V to 5.5 V, 32.768 kHz)	0.1397 μ s (at 4.0 V to 5.5 V, 14.32 MHz) 71.5 μ s (at 2.7 V to 5.5 V, 14.32 MHz internal frequency di Vision) 61 μ s (at 2.5 V to 5.5 V, 32.768 kHz)

■ Interrupts

RESET, Runaway, External 0 to 4, Timer 0 to 3, Timer 6, Capstan FG, Control, HSW, Cylinder(Drum) FG, Servo V-sync, Synchronous output, OSD, XDS, Serial 1, Serial 2, PWM 4, OSD V-sync

■ Timer Counter

Timer counter 0 : 8-bit \times 1 (timer function)

Clock source..... 1/4, 1/16 of system clock frequency

Interrupt source overflow of timer counter 0

Timer counter 1 : 8-bit \times 1 (timer function, linear timer counter function)

Clock source..... 1/4 of system clock frequency; CTL signal

Interrupt source overflow of timer counter 1

Timer counter 2 : 16-bit \times 1 (timer function, input capture (CTL specified edge), duty judgment of CTL signal)

Clock source..... 1/4, 1/16, 1/24 of system clock frequency

Interrupt source overflow of timer counter 2; input of CTL specified edge; underflow of timer 2 shift register 4-bit counter; coincidence of timer 2 shift register with timer 2 shift register compare register

Timer counter 3 : 16-bit \times 1 (timer function)

Clock source..... 1/4, 1/16 of system clock frequency

Interrupt source overflow of timer counter 3

Timer counter 5 : 19-bit \times 1 (watchdog, stable oscillation waiting function)

Clock source..... system clock

Watchdog interrupt source... 1/2¹⁶, 1/2¹⁹ of timer counter 5 frequency

Clear by stable oscillation ... after 256 counts by timer counter 5 (2¹⁸ counts of OSC oscillation clock)

Timer counter 6 : 16-bit \times 1 (clock function [max. 2 s])

Clock source..... 1/512 of OSC oscillation clock frequency; XI oscillation clock; 1/8, 1/128 of system clock frequency

Interrupt source 1/2¹³, 1/2¹⁴, 1/2¹⁵ overflow of timer counter 6

■ Serial interface

Serial 1 : 8-bit \times 1 (synchronous type)

(transfer direction of MSB/LSB selectable, start condition function)

Clock source..... 1/8, 1/16, 1/32, 1/64, 1/128, 1/256 of system clock frequency; NSBT1 pin input

Serial 2 : 8-bit \times 1 (I²C)

(master transmission/reception, slave transmission/reception)

Clock source..... 1/144 to 1/252 of system clock; SCK pin input

■ OSD

Display mode Menu(Internal synchronized) display, super impose(external synchronized) display
 Applicable broadcasting system.....NTSC, PAL, PAL-M, PAL-N
 Screen configuration 24 characters × 2n rows (n = 1 to 6)
 Character type max. 128 character types (variable, include special characters)
 Character size 12 × 18 dots (Vertical direction : 1 dot for 2H at not enlargement)
 Enlarged characters each × 2 settings in horizontal and vertical
 Character interpolation..... none
 Line background color 8-hue settable in the row unit at menu display
 Line background intensity..... 8 gradations settable in the row unit
 Screen background color..... 8-hue settable at omenu display
 Character color..... white
 Character intensity 8 gradations settable in the row unit
 Frame function 1-dot frame in 4 directions
 Frame intensity..... 4 gradations settable in the row unit
 Blinking..... none (covered by software)
 Inverted character..... settable in the character unit
 Halftone..... none
 Input composite video signal input (output level : 1 V[p-p] / 2 V[p-p])
 Clamp method sync tip clamp, clamp level in 4 levels
 Output composite video output
 Measure against image fluctuation..... built-in AFC circuit
 Dot clock 1/2 of OSC oscillation clock (automatic phase adjustment)

■ XDS

Built-in U.S. closed caption data slicer (optional 1 line data can be extracted.)

■ I/O Pins

I/O	56	Common use : 45
Input	1	Common use : 1

■ A/D converter

8-bit × 11-ch. (without S/H)

■ PWM

13-bit × 2-ch. (at repetition cycle 572 ms at 14.32 MHz),
 8-bit × 1-ch. (at repetition cycle 71.5 ms, 0.572 ms, 1.14 ms, 2.29 ms at 14.32 MHz)

■ ICR

16-bit × 2-ch.(Speed system),
 18-bit × 4-ch.(Phase system)

■ OCR

16-bit × 3 (Synchronous output × 2, Rec CTL × 1)

■ Special Ports

3-state output (PTO) VLP pin; CTL input; Capstan FG input; Cylinder(Drum) PG/FG inputs; HSW output; Head amp/ Rotary control outputs; output of 1/4 OSC oscillation clock (1 V[p-p])

■ ROM Correction

Correcting address designation : up to 3 addresses possible
 Correction method : correction program being saved in internal RAM

■ Electrical Characteristics (Supply current)

Parameter	Symbol	Condition	Limit			Unit
			min	typ	max	
Operating supply current	IDD1	14.32 MHz operation without load, VDD = 5 V		50	100	mA
	IDD2	1/1024 of 14.32 MHz operation without load, VDD = 2.7 V		2	5	mA
	IDD3	Stop of 14.32 MHz oscillation, VDD = 2.7 V 32 kHz oscillation operation without load		50	100	μA
Supply current at STOP	IDSP	Stop of oscillation without load, VDD = 5 V			10	μA
Supply current at HALT	IDHT0	14.32 MHz oscillation without load, VDD = 5 V		5	15	mA
	IDHT1	Stop of 14.32 MHz oscillation, VDD = 2.7 V 32 kHz oscillation operation without load		5	20	μA

(Ta = 25°C±2°C, VSS = 0 V)

■ Electrical Characteristics (A/D converter characteristics)

Parameter	Symbol	Condition	Limit			Unit
			min	typ	max	
Conversion relative error	ΔNLAD				±3	LSB
A/D Conversion Time	tAD	fosc = 14.32 MHz		8		μs
Analog Input Voltage					5	V

(Ta = 25°C±2°C, VDD = 5.0 V, VSS = 0 V)

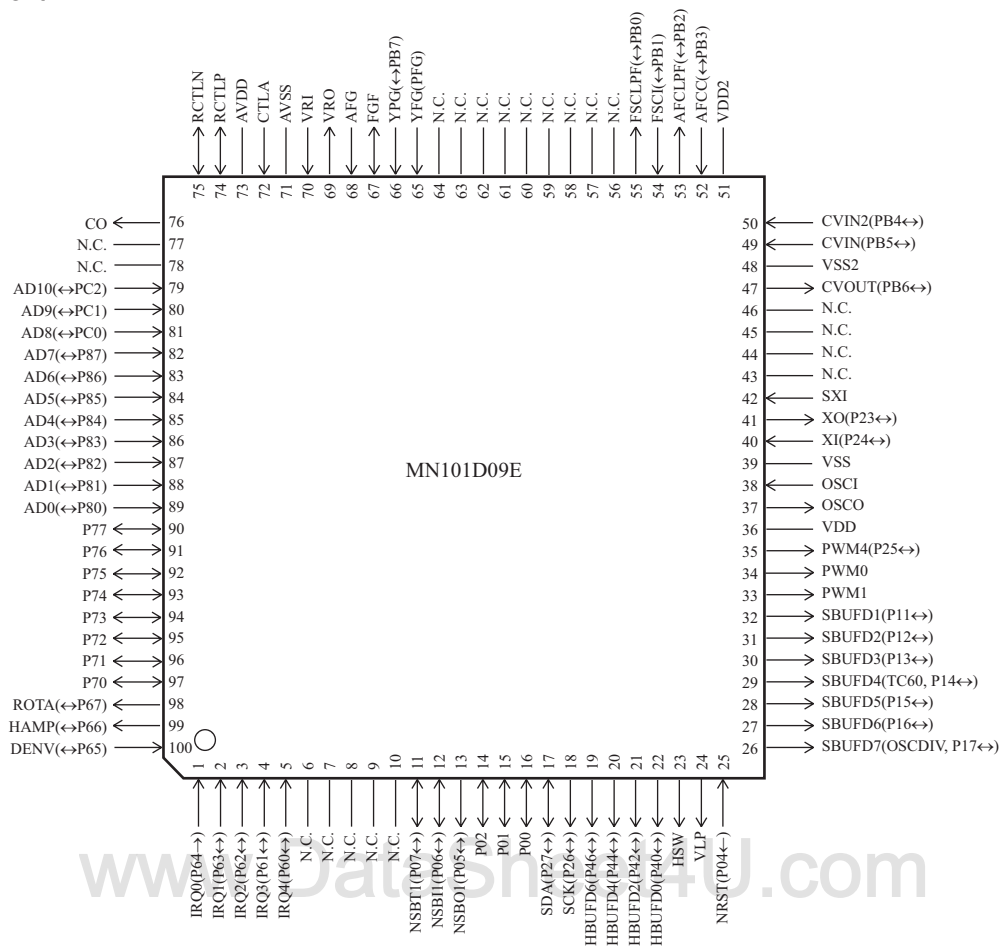
■ Development tools

In-circuit Emulator

PX-ICE101C/D + PX-PRB101D08-QFP100-P-1818B-M

www.DataSheet4U.com

■ Pin Assignment



QFP100-P-1818B

Request for your special attention and precautions in using the technical information and semiconductors described in this book

- (1) If any of the products or technical information described in this book is to be exported or provided to non-residents, the laws and regulations of the exporting country, especially, those with regard to security export control, must be observed.
- (2) The technical information described in this book is intended only to show the main characteristics and application circuit examples of the products, and no license is granted under any intellectual property right or other right owned by our company or any other company. Therefore, no responsibility is assumed by our company as to the infringement upon any such right owned by any other company which may arise as a result of the use of technical information described in this book.
- (3) The products described in this book are intended to be used for standard applications or general electronic equipment (such as office equipment, communications equipment, measuring instruments and household appliances).
Consult our sales staff in advance for information on the following applications:
 - Special applications (such as for airplanes, aerospace, automobiles, traffic control equipment, combustion equipment, life support systems and safety devices) in which exceptional quality and reliability are required, or if the failure or malfunction of the products may directly jeopardize life or harm the human body.
 - Any applications other than the standard applications intended.
- (4) The products and product specifications described in this book are subject to change without notice for modification and/or improvement. At the final stage of your design, purchasing, or use of the products, therefore, ask for the most up-to-date Product Standards in advance to make sure that the latest specifications satisfy your requirements.
- (5) When designing your equipment, comply with the range of absolute maximum rating and the guaranteed operating conditions (operating power supply voltage and operating environment etc.). Especially, please be careful not to exceed the range of absolute maximum rating on the transient state, such as power-on, power-off and mode-switching. Otherwise, we will not be liable for any defect which may arise later in your equipment.
 - ☐ Even when the products are used within the guaranteed values, take into the consideration of incidence of break down and failure mode, possible to occur to semiconductor products. Measures on the systems such as redundant design, arresting the spread of fire or preventing glitch are recommended in order to prevent physical injury, fire, social damages, for example, by using the products.
- (6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.
- (7) This book may be not reprinted or reproduced whether wholly or partially, without the prior written permission of Matsushita Electric Industrial Co., Ltd. Industrial Co., Ltd.